L Number	Hits	Search Text	DB	Time stamp
_	56117	((wafer or semiconductor or substrate) same plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/31 07:22
-	355	(plating near15 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:29
-	. 78	<pre>(((wafer or semiconductor or substrate) same plating)) and ((plating near15 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:11
-	370		USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30
_	79	<pre>((plating near25 (solution or fluid or liquid)) near15 (renew or regenerate or regeneration or recycle or reuse)) and (((wafer or semiconductor or substrate) same plating))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30
-	436	(plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:21
-	88	<pre>((plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse)) and (((wafer or</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:17
-	1177	semiconductor or substrate) same plating)) (plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:30
-	204	or reusing or recovery or recovering) ((plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovering))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/30 16:23
-	56117	and (((wafer or semiconductor or substrate) same plating)) ((wafer or semiconductor or substrate or circuir) same plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/30
_	70084	((wafer or semiconductor or substrate or circuit) same plating)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/30 16:34
	56117	<pre>(((wafer or semiconductor or substrate or circuit) same plating)) and (((wafer or semiconductor or substrate or circuir) same plating))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/30 16:25
_	298	(((wafer or semiconductor or substrate or circuit) same plating)) and ((plating near15 (solution or fluid or liquid)) near15 (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/30 16:25

	,			
~	355	((plating or metalizing) near15 (solution	USPAT;	2004/05/30
		or fluid or liquid)) near15 (renew or	US-PGPUB;	16:30
		regenerate or regeneration or recycle or	EPO; JPO;	
		reuse)	DERWENT	
-	1187	((plating or metalizing)near15 (solution	USPAT;	2004/05/30
		or fluid or liquid)) near15 (regenerating	US-PGPUB;	16:30
		or renewing or renew or regenerate or	EPO; JPO;	
		regeneration or recycle or reuse or	DERWENT	
		reusing or recycling or reusing or		•
•		recovery or recovering)		
_	1187	((plating or metalizing) near15 (solution	USPAT;	2004/05/30
		or fluid or liquid)) near15 (regenerating	US-PGPUB;	16:31
		or renewing or renew or regenerate or	EPO; JPO;	
		regeneration or recycle or reuse or	DERWENT;	!
		reusing or recycling or reusing or	IBM TDB	
		recovery or recovering)	_	
_	298	(((plating or metalizing)near15 (solution	USPAT;	2004/05/30
		or fluid or liquid)) near15 (regenerating	US-PGPUB;	16:31
		or renewing or renew or regenerate or	EPO; JPO;	•
		regeneration or recycle or reuse or	DERWENT;	
		reusing or recycling or reusing or	IBM TDB	
		recovery or recovering)) and (((wafer or	_	
		semiconductor or substrate or circuit)		
		same plating))		
_	1204	((plating or metalizing)near15 (solution	USPAT;	2004/05/31
		or fluid or liquid)) near15 (refresh or	US-PGPUB;	05:32
		refreshing or regenerating or renewing or	EPO; JPO;	
		renew or regenerate or regeneration or	DERWENT;	
		recycle or reuse or reusing or recycling	IBM TDB	
	ļ	or reusing or recovery or recovering)	_	
	309		USPAT;	2004/05/30
	•	or fluid or liquid)) near15 (refresh or	US-PGPUB;	16:33
		refreshing or regenerating or renewing or	EPO; JPO;	
		renew or regenerate or regeneration or	DERWENT;	
		recycle or reuse or reusing or recycling	IBM TDB	
		or reusing or recovery or recovering))	_	
		and (({wafer or semiconductor or		
		substrate or circuit) same plating))		
_	5865	((wafer or semiconductor or substrate or	USOCR	2004/05/30
		circuit) same plating)	1	16:34
-	98	((plating or metalizing)near15 (solution	USOCR	2004/05/30
		or fluid or liquid)) near15 (refresh or		16:35
		refreshing or regenerating or renewing or		
		renew or regenerate or regeneration or		
		recycle or reuse or reusing or recycling		
		or reusing or recovery or recovering)		
_	33		USOCR	2004/05/30
		circuit) same plating)) and (((plating or		16:35
		metalizing)near15 (solution or fluid or		
		liquid)) near15 (refresh or refreshing or		
ļ		regenerating or renewing or renew or		
		regenerate or regeneration or recycle or		
		reuse or reusing or recycling or reusing		
		or recovery or recovering))		2004/05/22
_	1204	((plating or metalizing) near15 (solution	USPAT;	2004/05/30
		or fluid or liquid)) near15 (refresh or	US-PGPUB;	17:21
-		refreshing or regenerating or renewing or	EPO; JPO;	
		renew or regenerate or regeneration or	DERWENT;	
		recycle or reuse or reusing or recycling	IBM_TDB	
1	2436	or reusing or recovery or recovering)	HCDAD:	2004/05/20
-	2436		USPAT;	2004/05/30 17:21
		plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or	US-PGPUB;	11:21
		refreshing or regenerating or renewing or	EPO; JPO; DERWENT;	
ļ		renew or regenerate or regeneration or	IBM TDB	
		recycle or reuse or reusing or recycling	101-100	
		or reusing or recovery or recovering)		
L	1		1	I

_	31	(((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or	USOCR	2004/05/30 17:22
		reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat)		
	242	(((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31
-	0	(brest near10 implants) same safe	USPAT	2004/05/30 22:35
-	6	(breast near10 implants) near15 safe	USPAT	2004/05/30 22:36
_	630	breast near10 implants	USPAT	2004/05/30 22:42
_	30	"car wash" and stinson and 134/\$.ccls.	USPAT	2004/05/31 03:53
-	2	("6391209").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 05:24
-	16	"4652352" and (volume or weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 05:25
-	0	"4652352" and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 05:27
_	5	(((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15	USPAT; US-PGPUB; EPO; JPO;	2004/05/31 05:31
		(refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	DERWENT; IBM_TDB	2004/05/21
	0	or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or vessel or vat) and ((volume or weight) near15 (sensor or detector or monitor or	USOCR	2004/05/31 05:32
	L	measure or indicator or probe))	L	<u> </u>

_	7	((plating or metalizing)near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/31 05:33
		or reusing or recovery or recovering) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe))	11111_1010	
-	1540	((metalizing or etching or etchant or electroplating plating) near25 (liquid or fluid or solution)) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:37
-	1290	probe)) ((metalizing or etching or etchant or electroplating plating) near25 (liquid or fluid or solution)) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe)) and (wafer or semiconductor or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:38
-	201	substrate) ((metalizing or etching or etchant or electroplating plating) near25 (liquid or fluid or solution)) and ((volume or weight) near15 (sensor or detector or monitor or measure or indicator or probe)) and (wafer or semiconductor or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 05:42
-	134	substrate) and (regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering) ((metalizing or etching or etchant or electroplating plating)) and ((volume or weight) near15 (sensor or detector or	USPAT; US-PGPUB; EPO; JPO;	2004/05/31 05:43
		monitor or measure or indicator or probe)) and (wafer or semiconductor or substrate) and ((regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering) near15 (liquid or fluid or solution))	DERWENT; IBM_TDB	
-	183	((metalizing or etching or etchant or electroplating plating)) and ((volume or weight) near15 (sensor or detector or monitor or measuring or measure or indicator or probe)) and (wafer or semiconductor or substrate) and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 06:12
		<pre>((regenerating or renewing or renew or regenerate or regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering) near15 (liquid or fluid or solution))</pre>		
-	5	("6569307" or "6077437" or "6024856") and ((volume or weight) near15 (sensor or detector or monitor or measuring or measure or indicator or probe))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 06:25
-	8	("4252621" or "5980771" or "4652352" or "6569307" or "4042444") and heater	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/05/31 06:50
	54	(((electroplating or etchant or etching or plating or metalizing) near15 (solution or fluid or liquid)) near15 (refresh or refreshing or regenerating or renewing or renew or regenerate or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/31 06:46
		regeneration or recycle or reuse or reusing or recycling or reusing or recovery or recovering)) and pump and filter and (reactor or container or receptacle or tank or sink or bath or	<u> </u>	
	<u> </u>	vessel or vat) and heater		

			USPAT;	2004/05/31
-	3	"6391209" and heater	US-PGPUB;	06:46
			EPO; JPO;	00.40
			DERWENT	
	25	("4252621" or "5980771" or "4652352" or	USPAT;	2004/05/31
_	. 23	"6569307" or "4042444") and (heated or	US-PGPUB;	06:55
		heating or heater)	EPO; JPO;	*****
		neating of heater,	DERWENT	
_	592	((wafer or semiconductor or substrate)	USPAT;	2004/05/31
	""	same plating) and 118/\$.ccls.	US-PGPUB;	07:23
			EPO; JPO;	
			DERWENT;	
		·	IBM TDB	
_	1114	(wafer or semiconductor or substrate)	USPAT;	2004/05/31
		and(electroplating or plating) and	US-PGPUB;	07:27
		118/\$.ccls.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	99	, (,,	USOCR	2004/05/31
		and(electroplating or plating) and		07:29
		118/\$.ccls.		
_	497	\ · · · · 1	USOCR	2004/05/31
		118/\$.ccls.		07:29
-	8945	1 '	USOCR .	2004/05/31
		118/\$.ccls.	TICDAM.	2004/05/31
_	20422	(electroplating or plating coating) and	USPAT; US-PGPUB;	07:34
		118/\$.ccls.	EPO; JPO;	07:34
		,	DERWENT	
	<u> </u>		DEVMENT	1